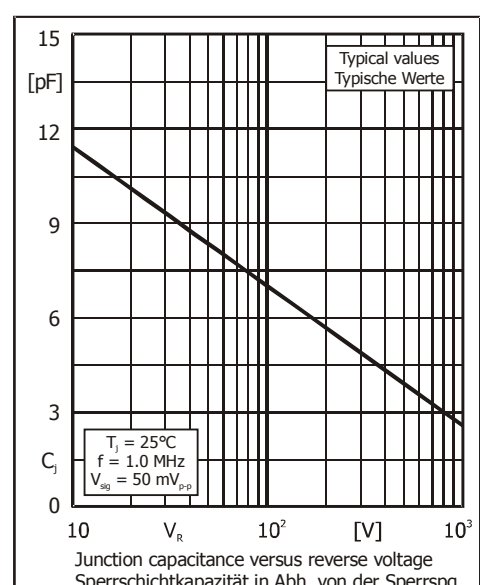
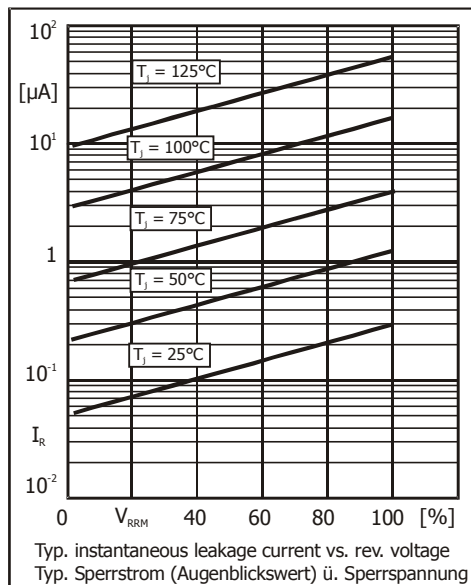
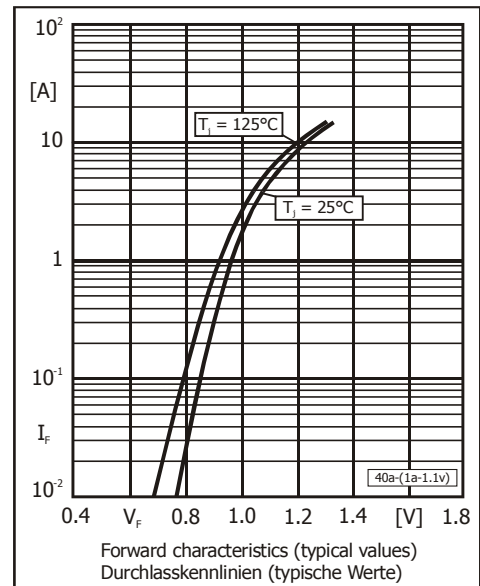
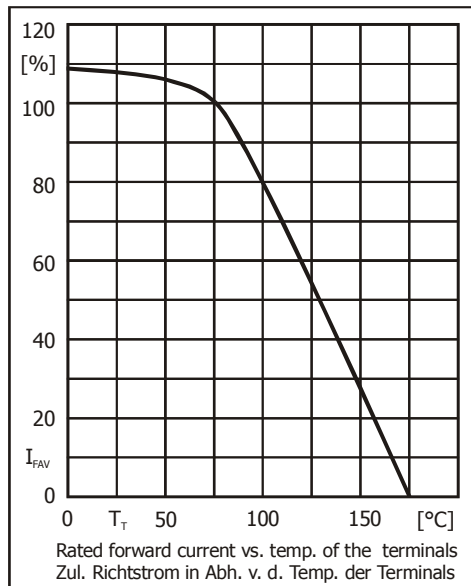




**Characteristics**
**Kennwerte**

Forward voltage – Durchlass-Spannung	$T_j = 25^\circ\text{C}$	$I_F = 1\text{ A}$	$V_F$	< 1.1 V
Leakage current Sperrstrom	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$	$I_R$	< 5 $\mu\text{A}$
	$T_j = 100^\circ\text{C}$	$V_R = V_{RRM}$	$I_R$	< 50 $\mu\text{A}$
Typical junction capacitance – Typische Sperrschichtkapazität	$V_R = 4\text{ V}$		$C_j$	10 pF
Reverse recovery time – Sperrverzug	$I_F = 0.5\text{ A}$ through/über $I_R = 1\text{ A}$ to $I_R = 0.25\text{ A}$		$t_{rr}$	typ. 1500 ns
Thermal resistance junction-ambient – Wärmewiderstand Sperrschicht-Umgebung			$R_{thA}$	< 45 K/W <sup>1)</sup>
Thermal resistance junction-terminal – Wärmewiderstand Sperrschicht-Anschluss			$R_{thT}$	< 10 K/W



**Disclaimer:** See data book page 2 or [website](#)  
**Haftungsausschluss:** Siehe Datenbuch Seite 2 oder [Internet](#)

1 Mounted on P.C. board with 25 mm<sup>2</sup> copper pads at each terminal  
 Montage auf Leiterplatte mit 25 mm<sup>2</sup> Kupferbelag (Lötpad) an jedem Anschluss